



Product Change Notification: BLAS-27MDGA724

Date:

09-May-2025

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors, Digital Signal Controllers

Notification Subject:

CCB 7203 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected dsPIC33EPxx, dsPIC33EVxx, MCP3913, MGC3030, PIC24EP12xx, PIC24EP25xx, PIC24FJ12xx, PIC24FJ64xx, PIC32MX11xx, PIC32MX12xx, PIC32MX13xx, PIC32MX15xx, PIC32MX17xx, PIC32MX21xx, PIC32MX22xx, PIC32MX23xx, PIC32MX25xx and PIC32MX27xx device families available in 28L SSOP (.209in) package at MTAI assembly site.

Affected CPNs:

[BLAS-27MDGA724_Affected_CPN_05092025.pdf](#)

[BLAS-27MDGA724_Affected_CPN_05092025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected dsPIC33EPxx, dsPIC33EVxx, MCP3913, MGC3030, PIC24EP12xx, PIC24EP25xx, PIC24FJ12xx, PIC24FJ64xx, PIC32MX11xx, PIC32MX12xx, PIC32MX13xx, PIC32MX15xx, PIC32MX17xx, PIC32MX21xx, PIC32MX22xx, PIC32MX23xx, PIC32MX25xx and PIC32MX27xx device families available in 28L SSOP (.209in) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
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Assembly Site	Microchip Technology Thailand (HQ) (MTAI)		Microchip Technology Thailand (HQ) (MTAI)	
Wire Material	Au		Au	CuPdAu
Die Attach Material	3280	8390A	3280	
Molding Compound Material	G600		G600	
Lead-Frame Material	CDA194		CDA194	
Lead-Frame Paddle Size	153 x 200 mils		153 x 200 mils	
DAP Surface Prep	Ag	Bare Cu	Bare Cu	

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as an additional bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 02 June 2025 (date code: 2523)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	January 2025					>	May 2025					June 2025				
Work Week	1	2	3	4	5		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date			X													
Qual Report Availability								X								

Final PCN Issue Date								X								
Estimated Implementation Date												X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: January 16, 2025: Issued initial notification.

May 9, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 2, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-27MDGA724_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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